

1206 SLOW BLOW SMD FUSES

L-KLS5-1206-12T Series 1A-15A 72V-63VDC/32V-24VDC

us RoHS **Ph** **HF**
E340427



Description

L-KLS5-1206-12T are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Electrical Characteristics

Rated Current	1.0In	2.0In	2.5In	3.0In	3.5In	10.0In
1A~3A	4hours mini.	1sec - 60sec	5sec max.	0.1sec - 3sec	-	0.2ms - 20ms
3.5A~5A	4hours mini.	-	5sec max.	0.1sec - 3sec	-	0.2ms - 20ms
7A~15A	4hours mini.				5sec max.	0.2ms - 10ms

Features

- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead free and Halogen free material

Applications

Secondary protection for space constrained applications:

- Cell phone
- DVD player
- Battery pack
- Hard disk drive
- Digital camera

Specification

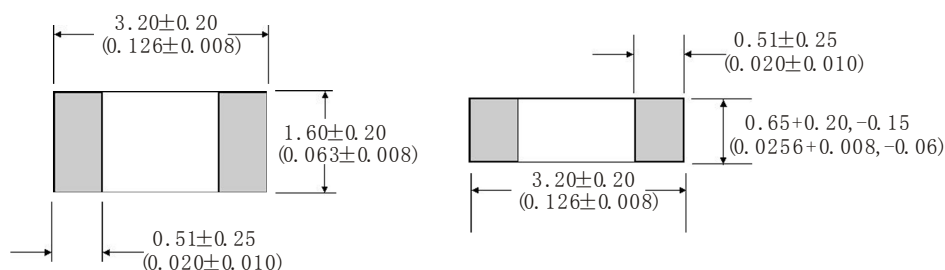
Rated Voltage (Vdc)				Rated Current (A)	Breaking Capacity	Typical Cold Resistance (mOhms) ²	Typical Voltage Drop (mV)	Typical Pre-Arcing P _t (A ² Sec) ³	Marking
72	72	63	32	1	100A@72/63/32Vdc 300A@24Vdc	485	550	0.18	H
				1.5		218	355	0.4	K
				2		133	310	1.1	N
				2.5		79	230	1.7	O
				3		49	185	2.2	P
				3.5		37	175	2.7	R
				4		33	160	3.2	S
				4.5		28	150	4.2	X
				5		22	135	6	T
				6		15.5	140	12	F
-	-	-	24	7		11.5	120	18	J
				8		8.0	100	18	V
				10		7.0	90	30	U
				12		5.9	85	45	W
				15		3.8	75	33	Y

*DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

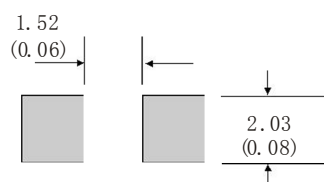
*DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 degrees

*Typical Pre-arcing P_t are measured at 10In Current

Dimensions (Unit: mm/inch)



Pad layout (Unit: mm/inch)



Soldering Parameters

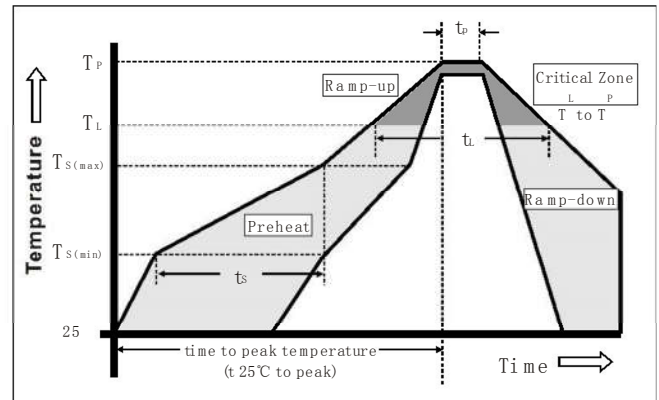
Reflow Condition		Pb-free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_p)	60 - 180 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		5°C/second max.
TS(max) to T_L - Ramp-up Rate		5°C/second max.
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 - 150 seconds
Peak Temperature (T^p)		260±0/-5°C
Time within 5° C of actual peak Temperature (t_p)		20 - 40 seconds
Ramp-down Rate		5° C/second max
Time 25° C to peak Temperature (T^p)		8 minutes max.
Do not exceed		260° C

Wave Soldering	260° C, 10 seconds max.
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Product Characteristics

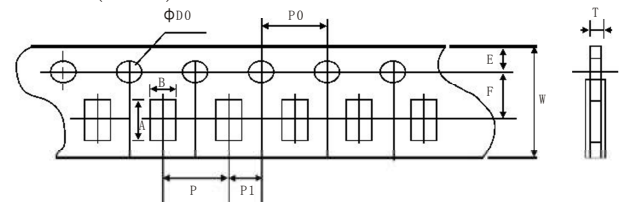
Materials	Body: Advanced High Temperature Substrate Terminations: 100% Tin over Nickel over Copper Element Cover Coat: Conformal Coating
Operating Temperature	-55° C to 125° C Consult temperature derating curve chart.
Thermal Shock	Withstands 5 cycles of -55° C to 125° C
Humidity	MIL-STD-202F, Method 103B, Condition D
Vibration	Per MIL-STD-202F, Method 201A
Insulation Resistance (After Opening)	Greater than 10,000 ohms
Resistance to Soldering Heat	MIL-STD-202G, Method 210F, Condition D

Temperature



Packaging

3,000 pieces of fuses in paper taper and reeled on a 178mm (7 inch) reel



Type	A	B	W	F	E
Spec	3.50±0.20	1.90±0.20	8.00±0.20	3.50±0.05	1.75±0.10
Type	P	P1	W	F	E
Spec	4.00±0.10	4.00±0.10	2.00±0.05	1.50±0.10	0.75±0.10

(Unit: mm)

Time Current Curve

